



STAC0912-250

RF power transistor from the LdmoST family of N-channel enhancement-mode lateral MOSFETs

Preliminary data

Features

- Excellent thermal stability
- Common source configuration push-pull
- $P_{OUT} = 250\text{ W}$ with 16 dB gain over 960 - 1215 MHz
- ST Air Cavity / STAC package

Description

The STAC0912-250 is a common source N-channel enhancement-mode lateral field-effect RF power transistor designed for mode -S, T-CAS, JTIDS, DME or TACAN applications in the 960 to 1215 MHz frequency range.

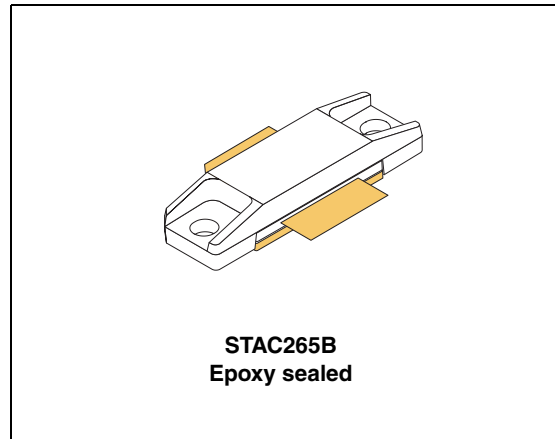


Figure 1. Pin connection

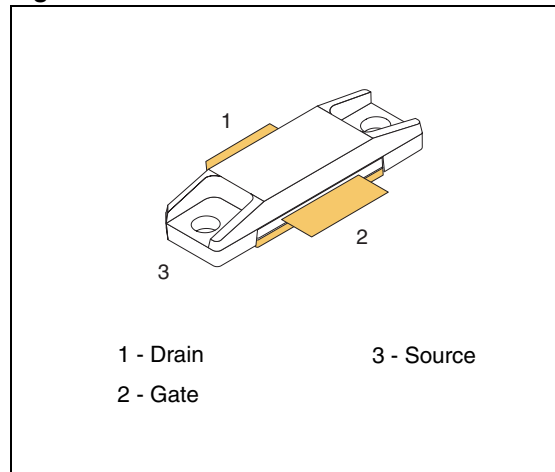


Table 1. Device summary

Order code	Package	Branding
STAC0912-250	STAC265B	0912-250

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1 Electrical data

1.1 Maximum ratings

$T_{CASE} = 25\text{ °C}$

Table 2. Absolute maximum ratings

Symbol	Parameter	Value	Unit
$V_{(BR)DSS}$	Drain-source voltage	80	V
V_{GS}	Gate-source voltage	± 20	V
P_{DISS}	Power dissipation (@ $T_C = 70\text{ °C}$)	928	W
T_J	Max. operating junction temperature	200	$^{\circ}\text{C}$
T_{STG}	Storage temperature	- 65 to + 150	$^{\circ}\text{C}$

1.2 Thermal data

Table 3. Thermal data @ 100 μs - 10 %

Symbol	Parameter	Value	Unit
R_{thJC}	Junction - case thermal resistance	0.14	$^{\circ}\text{C/W}$

2 Electrical characteristics

$T_{CASE} = + 25\text{ }^{\circ}\text{C}$

2.1 Static

Table 4. Static

Symbol	Test conditions		Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	$V_{GS} = 20\text{ V}$	$I_{DS} = 10\text{ mA}$	80			V
I_{DSS}	$V_{GS} = 0\text{ V}$	$V_{DS} = 28\text{ V}$			2	μA
I_{GSS}	$V_{GS} = 15\text{ V}$	$V_{DS} = 0\text{ V}$			1	μA
$V_{GS(Q)}$	$V_{DS} = 28\text{ V}$	$I_{DS} = 150\text{ mA}$	2.0		5.0	V
$V_{DS(ON)}$	$V_{GS} = 10\text{ V}$	$I_{DS} = 6\text{ A}$		0.9	1.2	V
G_{FS}	$V_{DS} = 10\text{ V}$	$I_{DS} = 6\text{ A}$	2.5			mho

2.2 Dynamic

$V_{DD} = 36\text{ V}$ $I_{dq} = 150\text{ mA}$ pulse width = 100 μsec duty cycle = 10 %

Table 5. Dynamic

Symbol	Test conditions		Min.	Typ.	Max.	Unit
Frequency			960		1215	MHz
P_{OUT}	$P_{IN} = 12\text{ W}$		250	285		W
G_{PS}	$P_{OUT} = 250\text{ W}$		14	16.3		dB
η_D	$P_{OUT} = 250\text{ W}$		50	58		%
T_r	Rise Time - $P_{OUT} = 250\text{ W}$				25	ns
T_f	Fall Time - $P_{OUT} = 250\text{ W}$				10	ns
Droop	$P_{OUT} = 250\text{ W}$				0.2	dB
Load Mismatch	All phase angles at $P_{OUT} = 250\text{ W}$				10:1	VSWR

Table 6. Reference data⁽¹⁾

Mode of operation	Pulse conditions	V _{DD} (V)	P _{OUT} (W)	Gain (dB)	Delta gain (dB)	Eff. (%)	Pulse droop (dB)	TR (nsec)	TF (nsec)	RTH _{J-C} (°C/W)
All modes	100µsec - 10%	36	250	16	0.7	58	0.1	25	5	0.14
TCAS 1030 - 1090 MHz	32µsec - 1%	36	250	16	0.3	57	0.1	25	5	0.06
Mode-S 1030 - 1090 MHz	128µsec - 2%	36	250	15.5	0.3	56	0.2	25	5	0.125
	340µsec - 1%	36	250	15.5	0.3	56	0.25	25	5	0.17

1. Typical RF performance measured in common source class-AB broadband circuit 960 MHz to 1215 MHz frequency band.
Th = 25 °C; RTH_{J-C} = 0.15°C/W; unless specified otherwise.

3 Impedance data

Figure 2. Impedance data

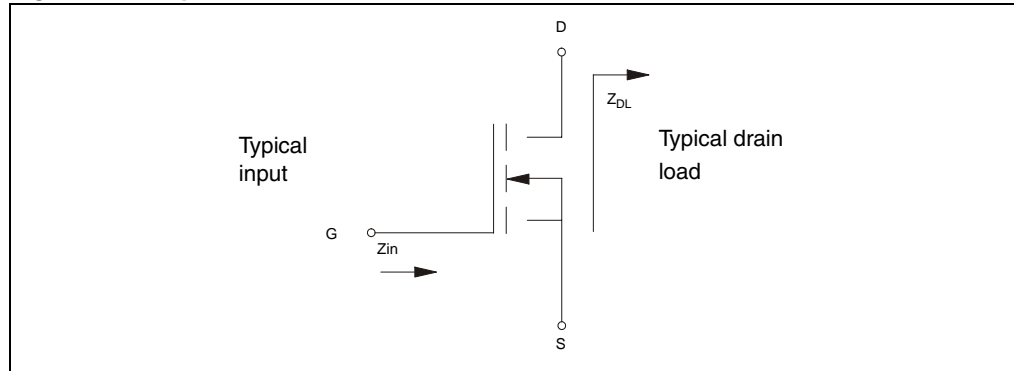


Table 7. Impedance data

Frequency (MHz)	Z_{source} (Ohm)	Z_{load} (Ohm)
960	$0.96+j0.75$	$2.2+j0.57$
1030	$1.01+j1.3$	$1.57+j0.97$
1090	$1.18+j1.73$	$1.25+j1.5$
1140	$1.29+j1.86$	$1.1+j1.88$
1215	$1.1+j1.9$	$1.01+j2.44$

4 Typical performance

Figure 3. Gain vs. output power

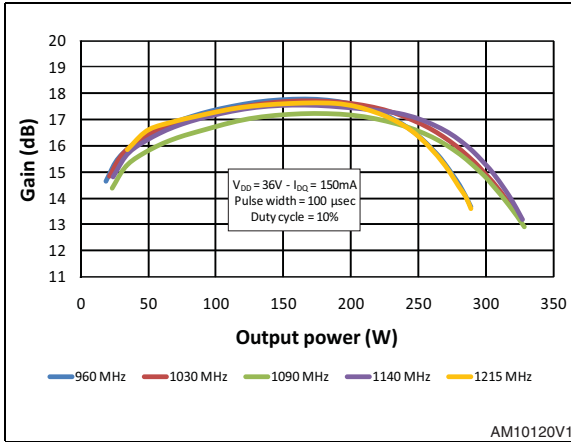


Figure 4. Efficiency vs. output power

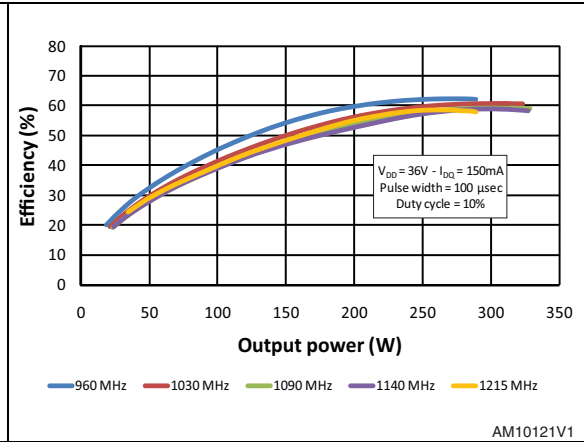
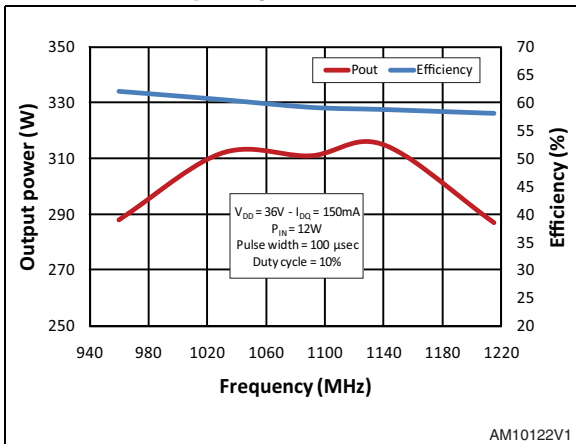


Figure 5. Output power and efficiency vs frequency



5 Circuit and BOM

Figure 6. Circuit

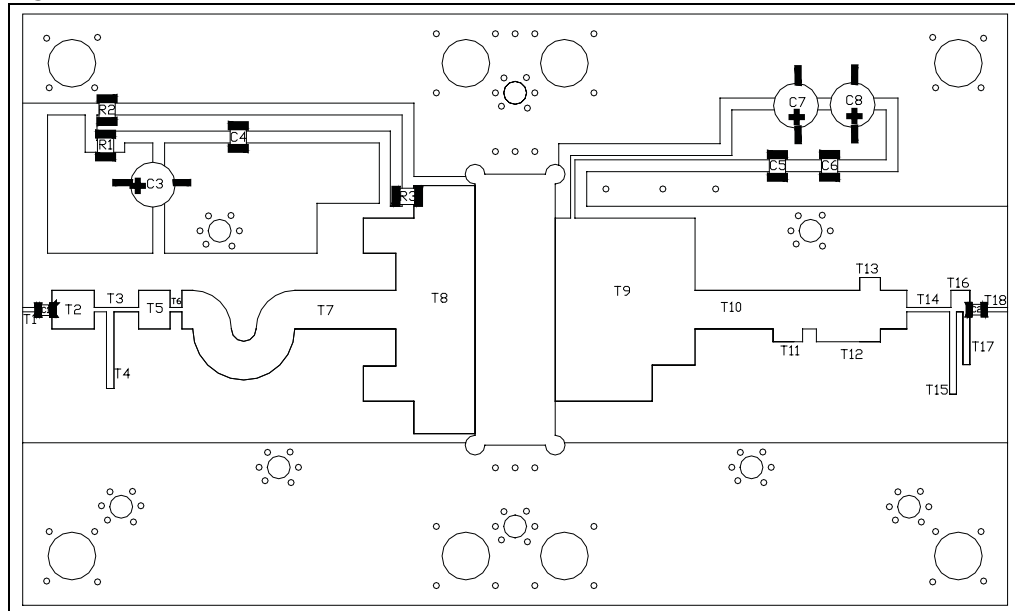


Table 8. Components list

Component	Description	Dimensions	Values
TL1	Stripline	L=0.085" W=0.022"	
TL2	Stripline	L=0.215" W=0.196"	
TL3	Stripline	L=0.225" W=0.022"	
TL4	Stripline	L=0.038" W=0.389"	
TL5	Stripline	L=0.160" W=0.196"	
TL6	Stripline	L=0.060" W=0.022"	
TL7	Stripline	L=1.382" W=0.196"	
TL8	Stripline	L ₁ =0.165" W ₁ =0.178" L ₂ =0.165" W ₂ =0.178" L ₃ =0.092" W ₃ =0.929" L ₄ =0.311" W ₄ =1.259"	
TL9	Stripline	L ₁ =0.492" W ₁ =0.929" L ₂ =0.217" W ₂ =0.764"	
TL10	Stripline	L=1.075" W=0.196"	
TL11	Stripline	L=0.150" W=0.065"	
TL12	Stripline	L=0.325" W=0.065"	
TL13	Stripline	L=0.105" W=0.065"	
TL14	Stripline	L=0.217" W=0.022"	

Table 8. Components list (continued)

Component	Description	Dimensions	Values
TL15	Stripline	L=0.035" W=0.418"	
TL16	Stripline	L=0.096" W=0.109"	
TL17	Stripline	L=0.035" W=0.268"	
TL18	Stripline	L=0.124" W=0.022"	
C1, C2	ATC100A300J chip capacitor		30pF
C3	220 μ F, 63V electrolytic capacitor		220 μ F
C4	ATC100B101 chip capacitor		100pF
C5, C6	ATC100B390 chip capacitor		39 pF
C17	220 μ F, 63V electrolytic capacitor		220 μ F
C20	100 μ F, 50V electrolytic capacitor		100 μ F
C21	1000 μ F, 63V electrolytic capacitor		1000 μ F
R1	CR1206-8W-361JB		360 Ohm
R2	CR1206-8W-621JB		620 Ohm
R3	CR1206-8W-122JB		1200 Ohm
Board Material	Rogers duroid 6010 Er = 10.2, Th = 0.64mm	3x5	in ²

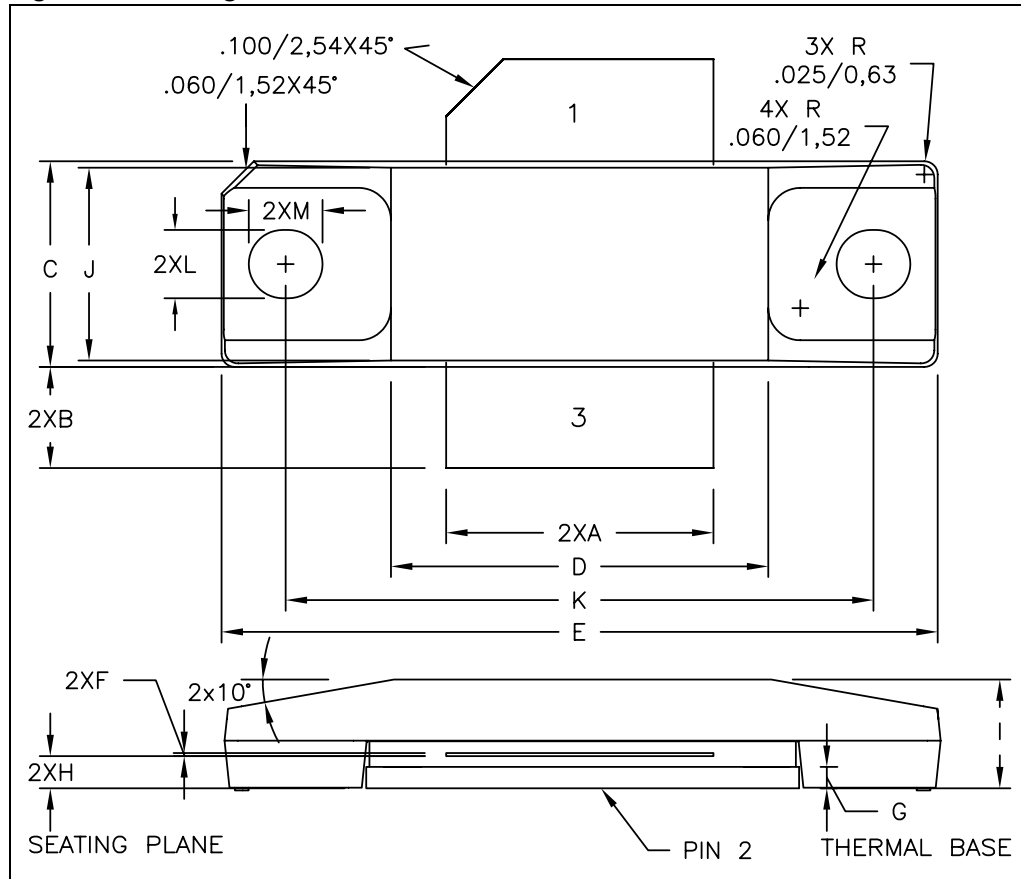
6 Package mechanical data

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK[®] packages, depending on their level of environmental compliance. ECOPACK[®] specifications, grade definitions and product status are available at: www.st.com. ECOPACK[®] is an ST trademark.

Table 9. STAC265B mechanical data

Dim.	mm.		
	Min.	Typ.	Max.
A	12.57		12.83
B	4.32		5.33
C	9.65		9.91
D	17.78		18.08
E	33.88		34.19
F	0.10		0.15
G		1.02	
H	1.45		1.70
I	4.83		5.33
J	9.27		9.52
K	27.69		28.19
L		3.23	
M		3.45	

Figure 7. Package dimensions



7 Revision history

Table 10. Document revision history

Date	Revision	Changes
20-Apr-2011	1	First release.
09-Aug-2011	2	Updated features on cover page. Updated P_{DISS} value in Table 2: Absolute maximum ratings , R_{thJC} value in Table 3: Thermal data @ 100 μs - 10 % . Updated typical and maximum values in Table 5: Dynamic Inserted new Table 6: Reference data and Section 3: Impedance data . Updated figures: 3 , 4 and 5 . Minor text changes.
13-Sep-2011	3	Added Section 5: Circuit and BOM .

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